

In The Specification

Please replace the paragraph at page 1, that begins with "CROSS-REFERENCE TO RELATED APPLICATIONS" with the following text:

A! -- This application is a division of Application No. 09/572,562, filed May 16, 2000, which issued as US Patent 6,335,224 on Jan. 1, 2002, "Protection of Microelectronic Devices During Packaging", by Peterson and Conley, which is herein incorporated by reference. --

✓ Marked-Up Version to Show Changes Made in the Specification

The paragraph at page 1 that begins with "CROSS-REFERENCE TO RELATED APPLICATIONS" was amended as follows:

- This application is a division of Application No. 09/572,562, filed May 16, 2000, which issued as US Patent 6,335,224 on Jan. 1, 2002, "Protection of Microelectronic Devices During Packaging", by Peterson and Conley, which is herein incorporated by reference. --

In The Claims

- Please amend the Claims as follows:

1. (AMENDED) A temporarily protected wafer, comprising:
 - a sensitive area disposed on a surface of the wafer; and
 - a vapor-deposited, water-insoluble temporary protective coating directly contacting and covering the sensitive area;
wherein the protective coating is insoluble in organic solvents;
wherein the coating remains in place during singulation of the wafer into individual device dies; and further
wherein a sufficient amount of the coating is removed to activate the sensitive area prior to completing packaging of the die.
2. The temporarily protected wafer of claim 1, wherein the sensitive area comprises a released MEMS device.
3. The temporarily protected wafer of claim 1, wherein the sensitive area comprises a pressure-sensitive microsensor.
4. The temporarily protected wafer of claim 1, wherein the sensitive area comprises a chemically sensitive microsensor.
5. The temporarily protected wafer of claim 1, wherein the sensitive area comprises a temperature-sensitive microsensor.

6. The temporarily protected wafer of claim 1, wherein the sensitive area comprises a released IMEMS device.

7. The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a vacuum vapor-deposited coating.

8. The temporarily protected wafer of claim 7, wherein the vacuum vapor-deposited coating comprises a parylene polymer.

9. The temporarily protected wafer of claim 8, wherein the parylene coating is selected from the group of parylene polymers consisting of poly-para-xylylene, poly-para-xylylene modified by the substitution of a chlorine atom for one aromatic hydrogen, and poly-para-xylylene modified by the substitution of a chlorine atom for two aromatic hydrogens.

10. (AMENDED) The temporarily protected wafer of claim 8, wherein the parylene coating comprises a copolymer compound coating formed by blending the a reactive parylene polymer monomer with a reactive material.

11. The temporarily protected wafer of claim 10, wherein the reactive material comprises a monomer containing an element selected from the group consisting of silicon, carbon, and fluorine, and combinations thereof.

12. The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises silicon dioxide, silicate glass, or silicon nitride.

13. The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a metal.

14. The temporarily protected wafer of claim 13, wherein the metal comprises aluminum or tungsten.

15. (CANCELLED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a vapor deposited organic material.

16. (CANCELLED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises cyanoacrylate.

17. (AMENDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises one or more materials selected from the group consisting of a carbon film, an amorphous carbon film, and a diamond-like carbon film.

18. The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a self-assembled monolayered material.

19. (AMENDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a material selected from perfluoropolyether, hexamethyldisilazane, and perfluorodecanoic carboxylic acid.

20. The temporarily protected wafer of claim 1, further comprising exposed bond pads.
21. The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited using a Chemical Vapor Deposition (CVD) process.
22. The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited using a Plasma Enhanced Chemical Vapor Deposition (PACVD) process.
23. The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited at essentially ambient temperature.
24. The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited by polymerizing a monomeric gas on at least the sensitive area.
25. (AMENDED) A temporarily protected die, comprising:
 - a sensitive area disposed on a surface of the die; and
 - a vapor-deposited, water-insoluble temporary protective coating directly contacting and covering the sensitive area;
 - wherein the protective coating is insoluble in organic solvents; and
 - wherein a sufficient amount of the coating is removed to activate the sensitive area prior to completing packaging of the die.
26. The temporarily protected die of claim 25, wherein the sensitive area comprises a released MEMS device.
27. The temporarily protected die of claim 26, wherein the temporary protective coating comprises a parylene polymer.
28. (AMENDED) A temporarily protected wafer, comprising:
 - a sensitive area disposed on a surface of the wafer comprising a released MEMS device having a released MEMS element;
 - a performance-enhancing coating disposed directly on the released MEMS element; and
 - a vapor-deposited, water-insoluble temporary protective coating disposed directly on top of the performance-enhancing coating;
 - wherein the coating remains in place during singulation of the wafer into individual device dies, and further wherein a sufficient amount of the coating is removed to release the MEMS element prior to completing packaging of the die, without removing the performance-enhancing coating.
29. (AMENDED) The temporarily protected wafer of claim 28, wherein the performance-enhancing coating is comprises one or more materials selected from the group consisting of an anti-stiction film, an adhesion-inhibiting film, a lubricant, and a nitrided-surface.

30. (AMENDED) The temporarily protected wafer of claim 28, wherein the performance-enhancing coating is comprises one or more materials selected from the group consisting of perfluoropolyether, hexamethyldisilazane, and perfluorodecanoic carboxylic acid.

31. (CANCELLED) A ~~partially packaged, temporarily protected microelectronic device, comprising:~~

a microelectronic device attached to a package;

a sensitive area disposed on the microelectronic device; and

a vapor-deposited, water-insoluble temporary protective coating covering the sensitive area; wherein a sufficient amount of the coating is removed to activate the sensitive area prior to completing packaging of the device.

32. (CANCELLED) The device of claim 31, wherein the sensitive area comprises a released MEMS element.

33. (CANCELLED) The device of claim 31, wherein the microelectronic device is electrically interconnected to the package.

34. (CANCELLED) The device of claim 33, wherein the microelectronic device is wirebonded to the package.

35. (NEW) The temporarily protected wafer of claim 1, wherein the temporary protective coating is insoluble in organic solvents heated to less than or equal to 150 C.

36. (NEW) The temporarily protected wafer of claim 1, wherein the temporary protective coating is excluded from covering any wafer streets.

37. (NEW) The protected die of claim 25, wherein the die is mechanically attached and electrically interconnected to a package.

38. (NEW) The die of claim 37, wherein the sensitive area comprises a released MEMS element.

39. (NEW) The die of claim 37, wherein the die is wirebonded to the package.

40. (NEW) The die of claim 37, wherein the die is flip-chip bonded to the package.

41. (NEW) The die of claim 38, wherein the temporary protective coating is sufficiently thick so as to immobilize the released MEMS element.

42. (NEW) The die of claim 38, wherein the temporary protective coating is sufficiently thin so as to not immobilize the released MEMS element.